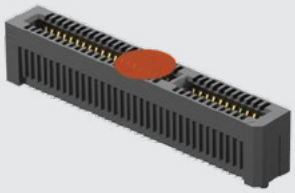
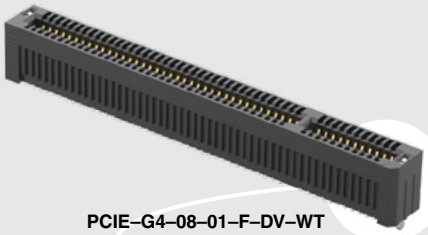
PCI EXPRESS®

(1.00 mm) .0394"

PCIE–G4–04–01–F–DV–A–K





PCIE–G4–08–01–F–DV–WT

PCIE-G4 SERIES

PCI EXPRESS® GEN 4 SOCKET

SPECIFICATIONS

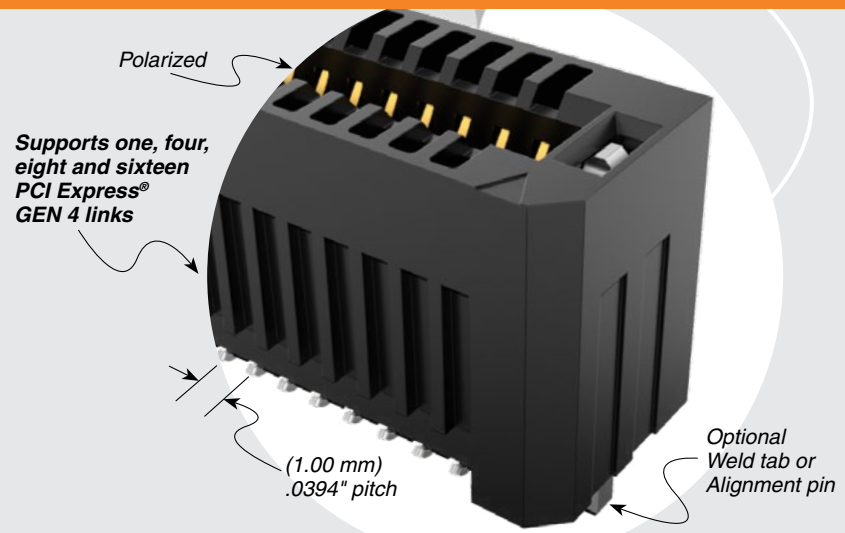
For complete specifications and recommended PCB layouts see www.samtec.com?PCIE-G4

Insulator Material:
LCP
Contact:
Copper Alloy
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
Testing Now!
Operating Temp:
Testing Now!

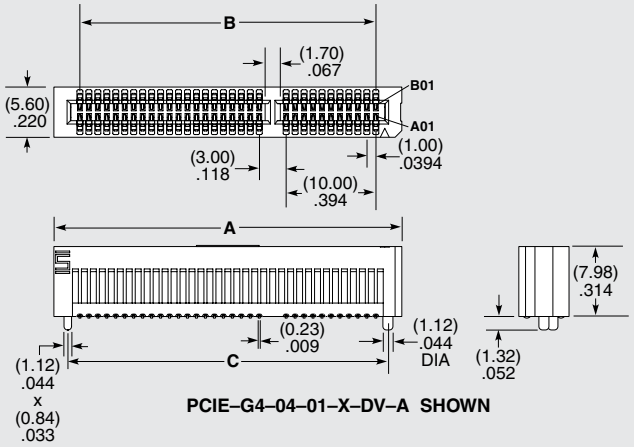
PROCESSING

Lead–Free Solderable:
Yes

Card Mates:
(1.60 mm) .062" card



PCIE	G4	NO. OF LANES	01	PLATING OPTION	DV	OPTION 1	OPTION 2	TR
		–01, –04, –08, –16		–F = Gold flash on contact, Matte Tin on tail –S = 30 µ" (0.76 µm) Gold on contact, Matte Tin on tail	–A = Alignment Pin (Not available with –WT) –WT = Weld Tab (Not available with –A)		–K = (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad	–TR = Tape & Reel (required for lanes –01, –04 & –08) Leave blank for tray packaging (only available for lanes –16)



PCIE–G4–04–01–X–DV–A SHOWN

NO. OF LANES	A	B	C (with –A)	C (with –WT)
–01	(24.80) .976	(19.00) .748	(21.70) .854	(23.30) .917
–04	(38.80) 1.528	(33.00) 1.299	(35.70) 1.406	(37.30) 1.469
–08	(55.80) 2.197	(50.00) 1.969	(52.70) 2.075	(54.30) 2.138
–16	(88.80) 3.496	(83.00) 3.268	(85.70) 3.374	(87.30) 3.437

PCI-SIG®, PCI Express® and the PCIe® design marks are registered trademarks and/or service marks of PCI-SIG.

Note:
Some lengths, styles and options are non-standard, non-returnable.